

Limeng Yin

List of Publications by Year in descending order

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18
papers

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19
times ranked

106
citing authors

| # | ARTICLE | IF | CITATIONS |
|----|--|-----|-----------|
| 1 | Molecular dynamics simulation of the interfacial evolution and whisker growth of copper-tin coating under electrothermal coupling. <i>Computational Materials Science</i> , 2022, 202, 110981. | 3.0 | 5 |
| 2 | Effect of Ti Content on the Microstructure and Properties of CoCrFeNiMnTi _x High Entropy Alloy. <i>Entropy</i> , 2022, 24, 241. | 2.2 | 9 |
| 3 | Effect of Cu Addition on the Microstructure and Mechanical Properties of Sn-58Bi-0.5Ag Solder Alloys. <i>Journal of Electronic Materials</i> , 2022, 51, 3552-3559. | 2.2 | 4 |
| 4 | Interfacial microstructure evolution and properties of Sn-0.3Ag-0.7Cu-xSiC solder joints. <i>Materials Science & Engineering A: Structural Materials: Properties, Microstructure and Processing</i> , 2021, 809, 140995. | 5.6 | 22 |
| 5 | Quantitative Correlation between Thermal Cycling and the Microstructures of X100 Pipeline Steel Laser-Welded Joints. <i>Materials</i> , 2020, 13, 121. | 2.9 | 13 |
| 6 | Microstructures and properties of Sn-0.3Ag-0.7Cu solder doped with graphene nanosheets. <i>Journal of Materials Science: Materials in Electronics</i> , 2020, 31, 1861-1867. | 2.2 | 10 |
| 7 | Effects of Location on the Microstructure and Mechanical Properties of Cu-8Al-2Ni-2Fe-2Mn Alloy Produced Through Wire Arc Additive Manufacturing. <i>Journal of Materials Engineering and Performance</i> , 2020, 29, 4733-4744. | 2.5 | 15 |
| 8 | Effects of Graphene Nanosheets on the Wettability and Mechanical Properties of Sn-0.3Ag-0.7Cu Lead-Free Solder. <i>Journal of Electronic Materials</i> , 2020, 49, 7394-7399. | 2.2 | 9 |
| 9 | Experimental and numerical simulation of mechanical behavior of micro-scale SAC305 solder joint based on joint height. <i>Welding in the World, Le Soudage Dans Le Monde</i> , 2020, 64, 2101-2108. | 2.5 | 1 |
| 10 | Effects of Joint Height on the Interfacial Microstructure and Mechanical Properties of Cu-Cored SAC305 Solder Joints. <i>Journal of Electronic Materials</i> , 2020, 49, 5391-5398. | 2.2 | 3 |
| 11 | Effect of Ni content on the creep properties of Cu/Sn-0.3Ag-0.7Cu/Cu solder micro-joints. <i>Journal of Materials Science: Materials in Electronics</i> , 2020, 31, 5462-5470. | 2.2 | 3 |
| 12 | Magnetocaloric effect in Ni-Fe-Mn-Sn microwires with nano-sized $\hat{\Gamma}^3$ precipitates. <i>Applied Physics Letters</i> , 2020, 116, . | 3.3 | 8 |
| 13 | The Evolution and Distribution of Microstructures in High-Energy Laser-Welded X100 Pipeline Steel. <i>Materials</i> , 2019, 12, 1762. | 2.9 | 5 |
| 14 | Prediction of weld formation in 5083 aluminum alloy by twin-wire CMT welding based on deep learning. <i>Welding in the World, Le Soudage Dans Le Monde</i> , 2019, 63, 947-955. | 2.5 | 14 |
| 15 | Microstructures and their distribution within HAZ of X80 pipeline steel welded using hybrid laser-MIG welding. <i>Welding in the World, Le Soudage Dans Le Monde</i> , 2018, 62, 721-727. | 2.5 | 14 |
| 16 | Microstructures and properties of Bi-10Ag high temperature solder doped with Cu element. <i>Microelectronics Reliability</i> , 2018, 80, 79-84. | 1.7 | 6 |
| 17 | Effects of Sn addition on the microstructure and properties of Bi-11Ag high-temperature solder. <i>Journal of Materials Science: Materials in Electronics</i> , 2018, 29, 12028-12035. | 2.2 | 7 |
| 18 | The effect of joint size on the creep properties of microscale lead-free solder joints at elevated temperatures. <i>Journal of Materials Science: Materials in Electronics</i> , 2013, 24, 1369-1374. | 2.2 | 20 |